$4 \text{ M SRAM} (256\text{-kword} \times 16\text{-bit})$

HITACHI

ADE-203-976B (Z) Rev. 2.0 Oct. 14, 1999

Description

The Hitachi HM62W16258B Series is 4-Mbit static RAM organized 262,144-word × 16-bit. HM62W16258B Series has realized higher density, higher performance and low power consumption by employing Hi-CMOS process technology. It offers low power standby power dissipation; therefore, it is suitable for battery backup systems. It is packaged in standard 44-pin plastic TSOPII.

Features

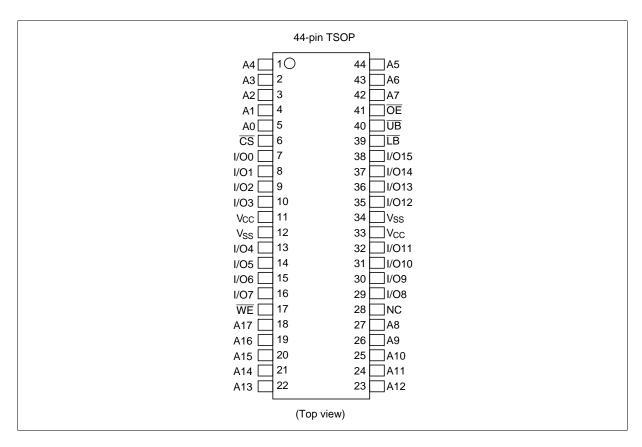
- Single 3.3 V supply: $3.3 \text{ V} \pm 0.3 \text{ V}$
- Fast access time: 55 ns/70 ns (max)
- Power dissipation:
 - Active: 9.9 mW (typ)
 - Standby: 3.3 μW (typ)
- Completely static memory.
 - No clock or timing strobe required
- Equal access and cycle times
- Common data input and output.
 - Three state output
- Battery backup operation.



Ordering Information

Type No.	Access time	Package
HM62W16258BLTT-5 HM62W16258BLTT-7	55 ns 70 ns	400-mil 44-pin plastic TSOPII (normal-bend type) (TTP-44DB)
HM62W16258BLTT-5SL HM62W16258BLTT-7SL	55 ns 70 ns	

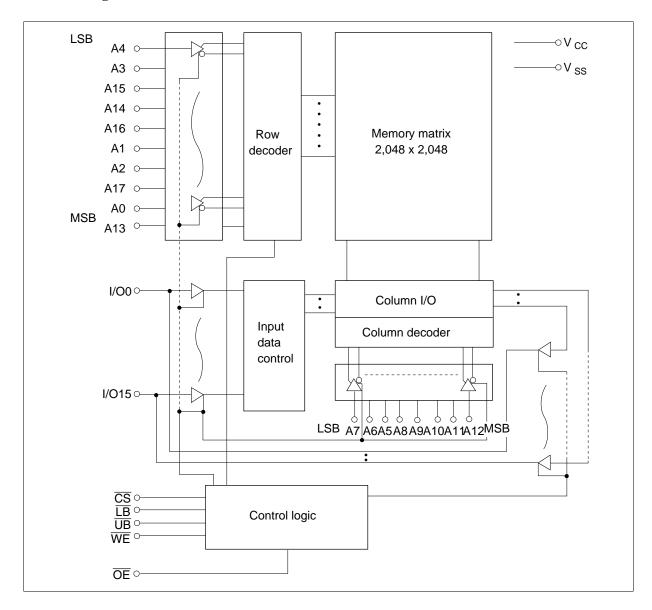
Pin Arrangement



Pin Description

Pin name	Function
A0 to A17	Address input
I/O0 to I/O15	Data input/output
CS	Chip select
WE	Write enable
ŌĒ	Output enable
LB	Lower byte select
ŪB	Upper byte select
V _{cc}	Power supply
V_{ss}	Ground
NC	No connection

Block Diagram



Operation Table

CS	WE	OE	UB	LB	I/O0 to I/O7	I/O8 to I/O15	Operation
Н	×	×	×	×	High-Z	High-Z	Standby
×	×	×	Н	Н	High-Z	High-Z	Standby
L	Н	L	L	L	Dout	Dout	Read
L	Н	L	Н	L	Dout	High-Z	Lower byte read
L	Н	L	L	Н	High-Z	Dout	Upper byte read
L	L	×	L	L	Din	Din	write
L	L	×	Н	L	Din	High-Z	Lower byte write
L	L	×	L	Н	High-Z	Din	Upper byte write
L	Н	Н	×	×	High-Z	High-Z	Output disable

Note: H: V_{IH} , L: V_{IL} , \times : V_{IH} or V_{IL}

Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Power supply voltage relative to V _{ss}	V _{cc}	-0.5 to + 4.6	V
Terminal voltage on any pin relative to V _{ss}	V _T	-0.5^{*1} to $V_{CC} + 0.3^{*2}$	V
Power dissipation	P _T	1.0	W
Storage temperature range	Tstg	-55 to +125	°C
Storage temperature range under bias	Tbias	-10 to +85	°C

Notes: 1. V_T min: -3.0 V for pulse half-width ≤ 30 ns.

2. Maximum voltage is +4.6 V.

DC Operating Conditions

Parameter	Symbol	Min	Тур	Max	Unit	Note
Supply voltage	V_{cc}	3.0	3.3	3.6	V	
	V _{SS}	0	0	0	V	
Input high voltage	V _{IH}	2.0	_	V _{cc} + 0.3	V	
Input low voltage	V _{IL}	-0.3	_	0.8	V	1
Ambient temperature range	Та	0	_	70	°C	

Note: 1. V_{IL} min: -3.0 V for pulse half-width ≤ 30 ns.

DC Characteristics

Paramete	r	Symbol	Min	Typ*1	Max	Unit	Test conditions
Input leaka	age current	I _{LI}	_	_	1	μΑ	$Vin = V_{SS}$ to V_{CC}
Output lea	kage current	I _{LO}	-	_	1	μΑ	$\frac{\overline{CS}}{\overline{LB}} = \frac{V_{IH}}{\overline{UB}} \text{ or } \overline{\overline{OE}} = V_{IH} \text{ or } \overline{\overline{WE}} = V_{IL}, \text{ or } \overline{\overline{LB}} = \overline{\overline{UB}} = V_{IH}, V_{I/O} = V_{SS} \text{ to } V_{CC}$
Operating	current	I_{cc}	_	_	20	mA	$\overline{\text{CS}} = V_{\text{IL}}$, Others = $V_{\text{IH}}/V_{\text{IL}}$, $I_{\text{I/O}} = 0$ mA
Average operating current	HM62W16258B-5	I _{CC1}	_	_	80	mA	Min. cycle, duty = 100%, $I_{I/O} = 0$ mA, $\overline{CS} = V_{IL}$, Others = V_{IH}/V_{IL}
	HM62W16258B-7	I _{CC1}	_	_	70	mA	
		I _{CC2}	_	3	15	mA	$\begin{split} &\text{Cycle time} = 1 \; \mu\text{s, duty} = 100\%, \\ &\text{I}_{\text{I/O}} = 0 \; \text{mA}, \overline{\text{CS}} \leq 0.2 \; \text{V}, \\ &\text{V}_{\text{IH}} \geq \text{V}_{\text{CC}} - 0.2 \; \text{V}, \; \text{V}_{\text{IL}} \leq 0.2 \; \text{V} \end{split}$
Standby co	urrent	I _{SB}	_	_	0.3	mA	$\overline{\text{CS}} = V_{IH}$
Standby co	Standby current		_	1	40	μΑ	$\frac{0 \text{ V} \le \text{Vin}}{\overline{\text{CS}}} \ge \text{V}_{\text{CC}} - 0.2 \text{ V}$
		I _{SB1} *3	_	1	20	μΑ	_
Output hig	h voltage	V _{OH}	2.4	_	_	V	I _{OH} = -1 mA
			$V_{cc} - 0.2$! —	_	V	$I_{OH} = -100 \mu A$
Output low	v voltage	V _{OL}	_	_	0.4	V	I _{OL} = 2 mA
				_	0.2	V	I _{OL} = 100 μA

Notes: 1. Typical values are at $V_{cc} = 3.0 \text{ V}$, $Ta = +25^{\circ}\text{C}$ and not guaranteed.

- 2. This characteristic is guaranteed only for L-version.
- 3. This characteristic is guaranteed only for L-SL version.

Capacitance (Ta = +25°C, f = 1.0 MHz)

Parameter	Symbol	Min	Тур	Max	Unit	Test conditions	Note
Input capacitance	Cin	_	_	8	pF	Vin = 0 V	1
Input/output capacitance	$C_{I/O}$	_	_	10	pF	$V_{I/O} = 0 V$	1

Note: 1. This parameter is sampled and not 100% tested.

AC Characteristics (Ta = 0 to +70°C, V_{CC} = 3.3 V \pm 0.3 V, unless otherwise noted.)

Test Conditions

• Input pulse levels: $V_{IL} = 0.4 \text{ V}$, $V_{IH} = 2.4 \text{ V}$

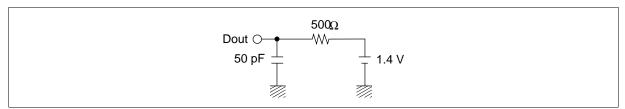
• Input rise and fall time: 5 ns

Input timing reference levels: 1.4 V

• Output timing reference levels: 1.4 V/1.4 V (HM62W16258B-5)

: 2.0 V/0.8 V (HM62W16258B-7)

Output load (Including scope and jig)



HM62W16258B

Read Cycle

-5 -7 **Symbol** Min Min **Parameter** Max Max Unit **Notes** Read cycle time 55 70 ns \mathbf{t}_{RC} Address access time 70 55 ns t_{AA} Chip select access time 55 70 ns t_{ACS} Output enable to output valid 40 35 ns t_{OE} Output hold from address change 10 10 ns t_{OH} $\overline{LB}, \overline{UB}$ access time 55 70 ns t_{BA} Chip select to output in low-Z 10 10 2, 3 t_{CLZ} ns LB, UB enable to low-z 5 5 2, 3 $t_{\scriptscriptstyle BLZ}$ ns Output enable to output in low-Z 5 5 2, 3 t_{OLZ} ns Chip deselect to output in high-Z 0 20 0 25 1, 2, 3 \mathbf{t}_{CHZ} ns LB, UB disable to high-Z $t_{\scriptscriptstyle BHZ}$ 0 20 0 25 ns 1, 2, 3 Output disable to output in high-Z 0 20 0 25 1, 2, 3 $\boldsymbol{t}_{\text{OHZ}}$ ns

Write Cycle

	16258B

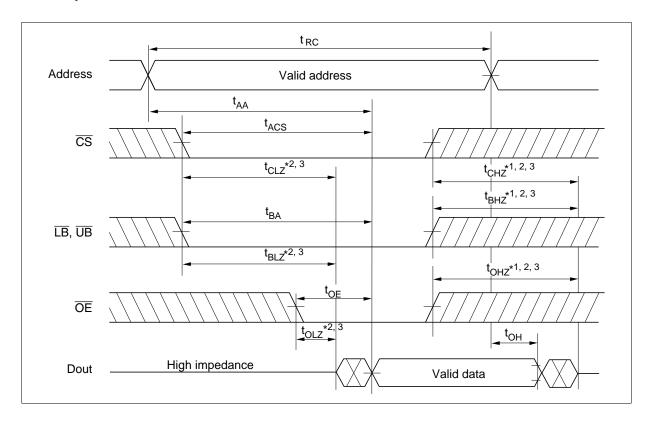
		-5		-7			
Parameter	Symbol	Min	Max	Min	Max	Unit	Notes
Write cycle time	t _{wc}	55	_	70	_	ns	
Address valid to end of write	t _{AW}	50	_	60	_	ns	
Chip selection to end of write	t _{cw}	50	_	60	_	ns	5
Write pulse width	t _{WP}	40	_	50	_	ns	4
LB, UB valid to end of write	t _{BW}	50	_	55	_	ns	
Address setup time	t _{AS}	0	_	0	_	ns	6
Write recovery time	t _{wR}	0	_	0	_	ns	7
Data to write time overlap	t _{DW}	25	_	30	_	ns	
Data hold from write time	t _{DH}	0	_	0	_	ns	
Output active from end of write	t _{ow}	5	_	5	_	ns	2
Output disable to output in High-Z	t _{OHZ}	0	20	0	25	ns	1, 2
Write to output in high-Z	t _{WHZ}	0	20	0	25	ns	1, 2

Notes: 1. t_{CHZ} , t_{OHZ} , t_{WHZ} and t_{BHZ} are defined as the time at which the outputs achieve the open circuit conditions and are not referred to output voltage levels.

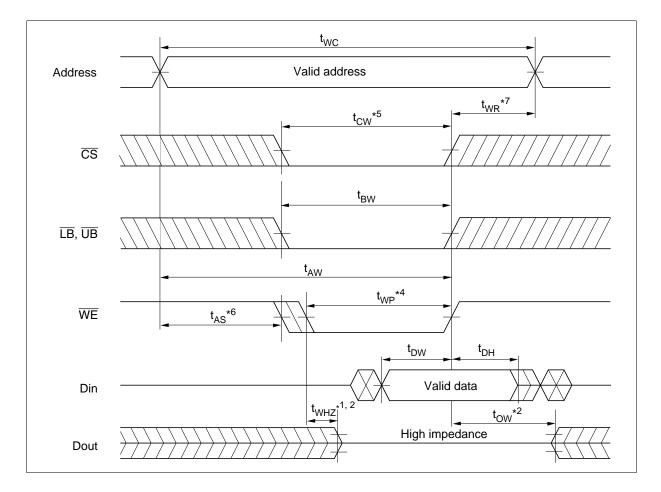
- 2. This parameter is sampled and not 100% tested.
- 3. At any given temperature and voltage condition, t_{HZ} max is less than t_{LZ} min both for a given device and from device to device.
- 4. A write occures during the overlap of a low \overline{CS} , a low \overline{WE} and a low \overline{LB} or a low \overline{UB} . A write begins at the latest transition among \overline{CS} going low, \overline{WE} going low and \overline{LB} going low or \overline{UB} going low. A write ends at the earliest transition among \overline{CS} going high, \overline{WE} going high and \overline{LB} going high or \overline{UB} going high. t_{WP} is measured from the beginning of write to the end of write.
- 5. t_{CW} is measured from the later of \overline{CS} going low to the end of write.
- 6. $t_{\mbox{\scriptsize AS}}$ is measured from the address valid to the beginning of write.
- 7. t_{WR} is measured from the earliest of \overline{CS} or \overline{WE} going high to the end of write cycle.

Timing Waveform

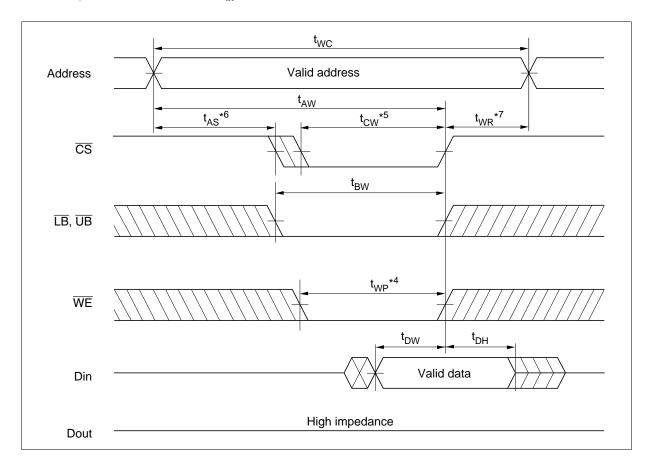
Read Cycle



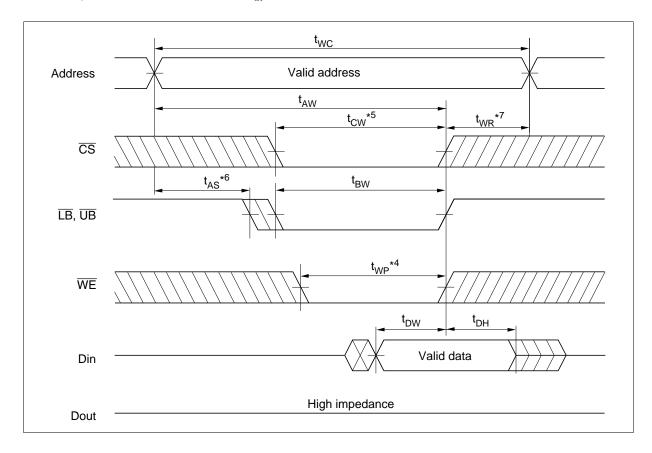
Write Cycle (1) $(\overline{\text{WE}} \text{ Clock})$



Write Cycle (2) ($\overline{\text{CS}}$ Clock, $\overline{\text{OE}} = V_{\text{IH}}$)



Write Cycle (3) (\overline{LB} , \overline{UB} Clock, $\overline{OE} = V_{IH}$)



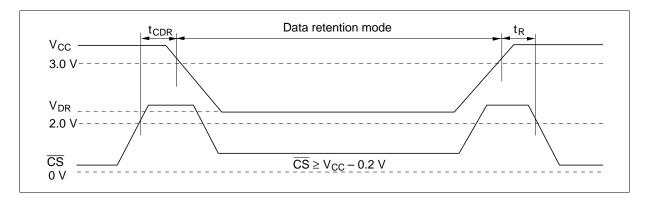
Low V_{cc} Data Retention Characteristics (Ta = 0 to +70°C)

Parameter	Symbol	Min	Typ*4	Max	Unit	Test conditions ^{*3}
V _{cc} for data retention	V_{DR}	2.0	_	_	V	$\begin{array}{c} \text{Vin} \geq 0\text{V} \\ \text{(1)} \ \overline{\text{CS}} \geq \text{V}_{\text{CC}} - 0.2 \text{ V or} \\ \text{(2)} \ \overline{\text{LB}} = \overline{\text{UB}} \geq \text{V}_{\text{CC}} - 0.2 \text{ V} \\ \overline{\text{CS}} \leq 0.2 \text{ V} \end{array}$
Data retention current	I _{CCDR} *1	_	0.8	20	μΑ	$\begin{aligned} V_{\text{CC}} &= 3.0 \text{ V, Vin} \ge 0\text{V} \\ \text{(1)} & \overline{\text{CS}} \ge V_{\text{CC}} - 0.2 \text{ V or} \\ \text{(2)} & \overline{\text{LB}} = \overline{\text{UB}} \ge V_{\text{CC}} - 0.2 \text{ V} \\ & \overline{\text{CS}} \le 0.2 \text{ V} \end{aligned}$
	I _{CCDR} *2	_	8.0	10	μΑ	
Chip deselect to data retention time	t _{CDR}	0	_	_	ns	See retention waveform
Operation recovery time	t _R	$t_{\text{RC}}^{5}}$	_	_	ns	_

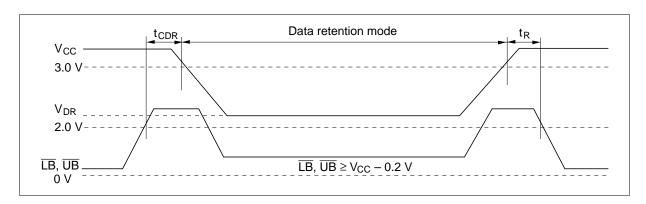
Notes: 1. This characteristic is guaranteed only for L-version, 10 μA max. at Ta = 0 to +40°C.

- 2. This characteristic is guaranteed only for L-SL version, 5 μ A max. at Ta = 0 to +40°C.
- 3. \overline{CS} controls address buffer, \overline{WE} buffer, \overline{OE} buffer, \overline{LB} , \overline{UB} buffer and Din buffer. If \overline{CS} controls data retention mode, Vin levels (address, \overline{WE} , \overline{OE} , \overline{LB} , \overline{UB} , \overline{UB} , \overline{UO}) can be in the high impedance state. If \overline{LB} , \overline{UB} controls data retention mode, \overline{LB} , \overline{UB} must be $\overline{LB} = \overline{UB} \ge V_{CC} 0.2 \text{ V}$, \overline{CS} must be $\overline{CS} \le 0.2 \text{ V}$. The other input levels (address, \overline{WE} , \overline{OE} , \overline{IO}) can be in the high impedance state.
- 4. Typical values are at V_{cc} = 3.0 V, Ta = +25 °C and not guaranteed.
- 5. t_{RC} = read cycle time.

Low V_{CC} Data Retention Timing Waveform (1) (\overline{CS} Controlled)

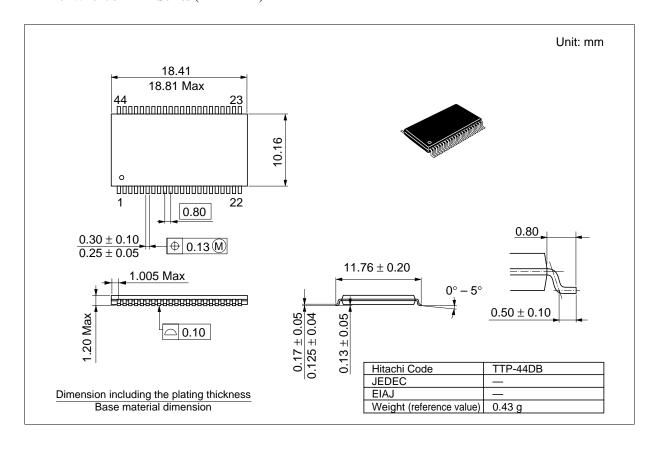


Low V_{CC} Data Retention Timing Waveform (2) $(\overline{LB},\overline{UB}$ Controlled)



Package Dimensions

HM62W16258BLTT Series (TTP-44DB)



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